

September 1995

**Radiation Hardened  
Dual 4-Input Multiplexer****Features**

- 3 Micron Radiation Hardened SOS CMOS
- Total Dose 200K RAD (Si)
- SEP Effective LET No Upsets:  $>100$  MEV-cm $^2$ /mg
- Single Event Upset (SEU) Immunity  $< 2 \times 10^{-9}$  Errors/Bit-Day (Typ)
- Dose Rate Survivability:  $>1 \times 10^{12}$  RAD (Si)/s
- Latch-Up Free Under Any Conditions
- Fanout (Over Temperature Range)
  - Bus Driver Outputs - 15 LSTTL Loads
- Military Temperature Range: -55°C to +125°C
- Significant Power Reduction Compared to LSTTL ICs
- DC Operating Voltage Range: 4.5V to 5.5V
- Input Logic Levels
  - VIL = 0.3 VCC Max
  - VIH = 0.7 VCC Min
- Input Current Levels  $I_i \leq 5\mu A$  at VOL, VOH

**Description**

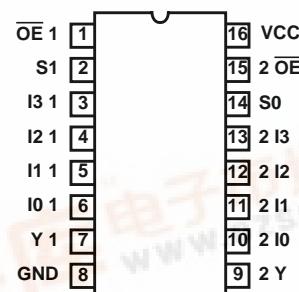
The Intersil HCS253MS is a Radiation Hardened 4-to-1 line selector multiplexer having three-state outputs. One of four sources for each section is selected by the common select inputs S0 and S1. When the output enable (1OE or 2OE) is HIGH, the output is in the high impedance state.

The HCS253MS utilizes advanced CMOS/SOS technology to achieve high-speed operation. This device is a member of radiation hardened, high-speed, CMOS/SOS Logic Family.

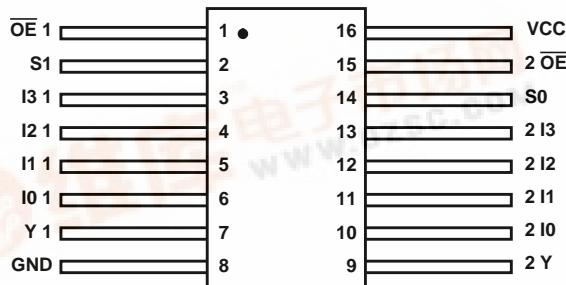
The HCS253MS is supplied in a 16 lead Ceramic flatpack (K suffix) or a SBDIP Package (D suffix).

**Pinouts**

16 LEAD CERAMIC DUAL-IN-LINE  
METAL SEAL PACKAGE (SBDIP)  
MIL-STD-1835 CDIP2-T16, LEAD FINISH C  
TOP VIEW



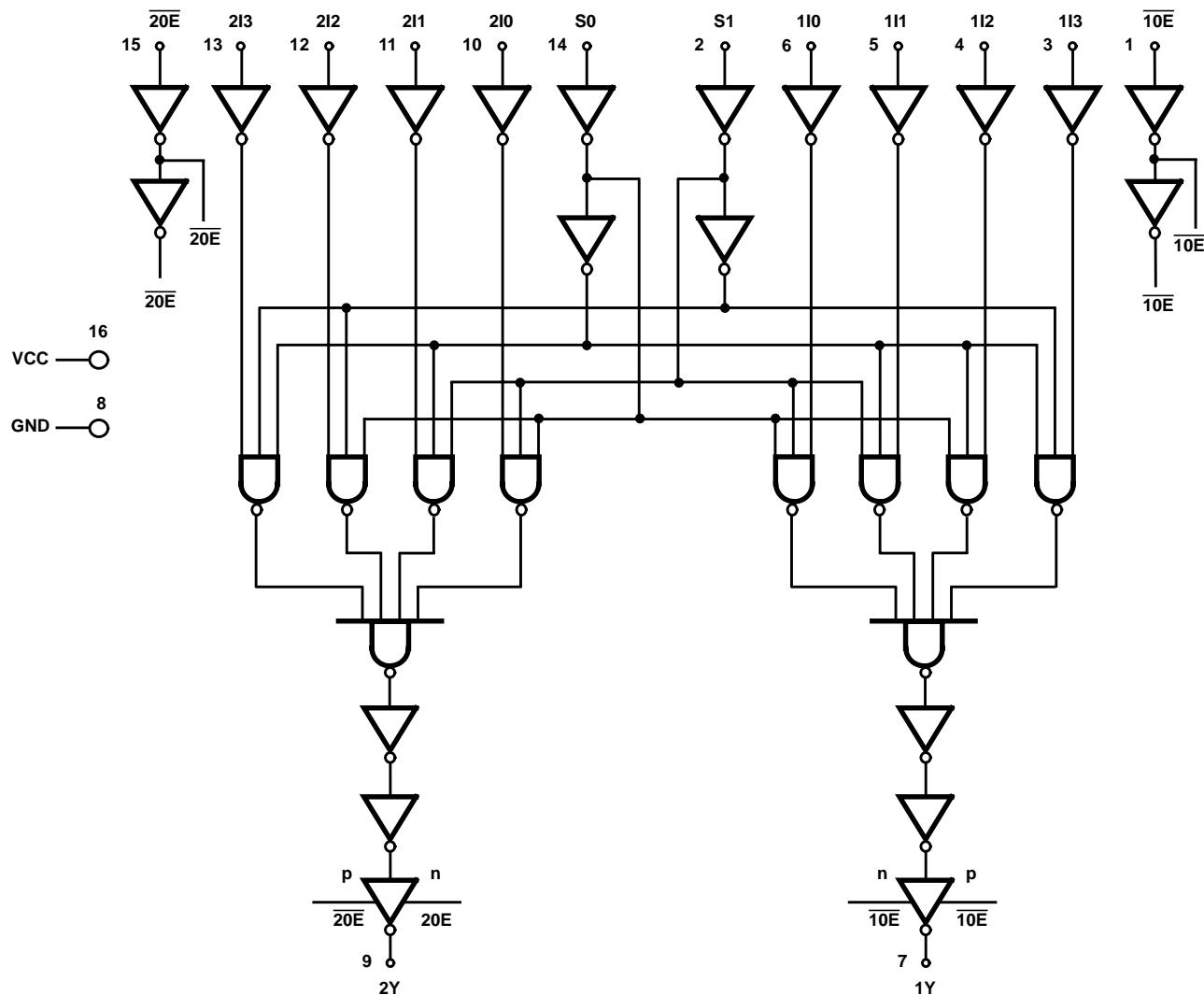
16 LEAD CERAMIC METAL SEAL  
FLATPACK PACKAGE (FLATPACK)  
MIL-STD-1835 CDIP4-F16, LEAD FINISH C  
TOP VIEW

**Ordering Information**

PART NUMBER	TEMPERATURE RANGE	SCREENING LEVEL	PACKAGE
HCS253DMSR	-55°C to +125°C	Intersil Class S Equivalent	16 Lead SBDIP
HCS253KMSR	-55°C to +125°C	Intersil Class S Equivalent	16 Lead Ceramic Flatpack
HCS253D/Sample	+25°C	Sample	16 Lead SBDIP
HCS253K/Sample	+25°C	Sample	16 Lead Ceramic Flatpack
HCS253HMSR	+25°C	Die	Die

# HCS253MS

## Functional Diagram



TRUTH TABLE

SELECT INPUTS		DATA INPUTS				OUTPUT ENABLE	OUTPUT
S1	S0	I0	I1	I2	I3	OE	Y
X	X	X	X	X	X	H	Z
L	L	L	X	X	X	L	L
L	L	H	X	X	X	L	H
L	H	X	L	X	X	L	L
L	H	X	H	X	X	L	H
H	L	X	X	L	X	L	L
H	L	X	X	H	X	L	H
H	H	X	X	X	L	L	L
H	H	X	X	X	H	L	H

Select inputs S0 and S1 are common to both sections

H = High Level, L = Low Level, X = Immaterial, Z = High Impedance (Off)

## Specifications HCS253MS

Absolute Maximum Ratings			Reliability Information				
Supply Voltage (VCC).....	-0.5V to +7.0V		Thermal Resistance $\theta_{JA}$		$\theta_{JC}$		
Input Voltage Range, All Inputs .....	-0.5V to VCC +0.5V		SBDIP Package.....	73°C/W	24°C/W		
DC Input Current, Any One Input .....	$\pm 10\text{mA}$		Ceramic Flatpack Package .....	114°C/W	29°C/W		
DC Drain Current, Any One Output.....	$\pm 25\text{mA}$		Maximum Package Power Dissipation at +125°C Ambient				
(All Voltage Reference to the VSS Terminal)			SBDIP Package.....		0.68W		
Storage Temperature Range (TSTG).....	-65°C to +150°C		Ceramic Flatpack Package .....		0.44W		
Lead Temperature (Soldering 10sec).....	+265°C		If device power exceeds package dissipation capability, provide heat sinking or derate linearly at the following rate:				
Junction Temperature (TJ) .....	+175°C		SBDIP Package.....		13.7mW/°C		
ESD Classification .....	Class 1		Ceramic Flatpack Package .....		8.8mW/°C		
CAUTION: As with all semiconductors, stress listed under "Absolute Maximum Ratings" may be applied to devices (one at a time) without resulting in permanent damage. This is a stress rating only. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. The conditions listed under "Electrical Performance Characteristics" are the only conditions recommended for satisfactory device operation..							
Operating Conditions							
Supply Voltage .....	+4.5V to +5.5V		Input Low Voltage (VIL).....	0.0V to 30% of VCC			
Input Rise and Fall Times at 4.5V VCC (TR, TF) .....	500ns Max		Input High Voltage (VIH) .....	70% of VCC to VCC			
Operating Temperature Range (T <sub>A</sub> ) .....	-55°C to +125°C						
TABLE 1. DC ELECTRICAL PERFORMANCE CHARACTERISTICS							
PARAMETER	SYMBOL	(NOTE 1) CONDITIONS	GROUP A SUB- GROUPS	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Quiescent Current	ICC	VCC = 5.5V, VIN = VCC or GND	1	+25°C	-	40	µA
			2, 3	+125°C, -55°C	-	750	µA
Output Current (Sink)	IOL	VCC = 4.5V, VIH = 4.5V, VOUT = 0.4V, VIL = 0V	1	+25°C	7.2	-	mA
			2, 3	+125°C, -55°C	6.0	-	mA
Output Current (Source)	IOH	VCC = 4.5V, VIH = 4.5V, VOUT = VCC -0.4V, VIL = 0V	1	+25°C	-7.2	-	mA
			2, 3	+125°C, -55°C	-6.0	-	mA
Output Voltage Low	VOL	VCC = 4.5V, VIH = 3.15V, IOL = 50µA, VIL = 1.35V	1, 2, 3	+25°C, +125°C, -55°C	-	0.1	V
			1, 2, 3	+25°C, +125°C, -55°C	-	0.1	V
Output Voltage High	VOH	VCC = 4.5V, VIH = 3.15V, IOH = -50µA, VIL = 1.35V	1, 2, 3	+25°C, +125°C, -55°C	VCC -0.1	-	V
			1, 2, 3	+25°C, +125°C, -55°C	VCC -0.1	-	V
Input Leakage Current	IIN	VCC = 5.5V, VIN = VCC or GND	1	+25°C	-	$\pm 0.5$	µA
			2, 3	+125°C, -55°C	-	$\pm 5.0$	µA
Three-State Output Leakage Current	IOZ	VCC = 5.5V, Applied Voltage = 0V or VCC	1	+25°C	-	$\pm 1.0$	µA
			2, 3	+125°C, -55°C	-	$\pm 50$	µA
Noise Immunity Functional Test	FN	VCC = 4.5V, VIH = 0.7 (VCC), VIL = 0.3 (VCC) (Note 2)	7, 8A, 8B	+25°C, +125°C, -55°C	-	-	-
NOTES:							
1. All voltages reference to device GND.							
2. For functional tests, VO $\geq$ 4.0V is recognized as a logic "1", and VO $\leq$ 0.5V is recognized as a logic "0".							

## Specifications HCS253MS

TABLE 2. AC ELECTRICAL PERFORMANCE CHARACTERISTICS

PARAMETER	SYMBOL	(NOTES 1, 2) CONDITIONS	GROUP A SUB- GROUPS	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Select to Output	TPHL TPLH	VCC = 4.5V	9	+25°C	2	26	ns
			10, 11	+125°C, -55°C	2	31	ns
Data to Output	TPHL	VCC = 4.5V	9	+25°C	2	19	ns
			10, 11	+125°C, -55°C	2	22	ns
	TPLH	VCC = 4.5V	9	+25°C	2	21	ns
			10, 11	+125°C, -55°C	2	24	ns
Enable to Output	TPZH	VCC = 4.5V	9	+25°C	2	17	ns
			10, 11	+125°C, -55°C	2	20	ns
	TPZL	VCC = 4.5V	9	+25°C	2	15	ns
			10, 11	+125°C, -55°C	2	17	ns
Disable to Output	TPHZ	VCC = 4.5V	9	+25°C	2	18	ns
			10, 11	+125°C, -55°C	2	19	ns
	TPLZ	VCC = 4.5V	9	+25°C	2	16	ns
			10, 11	+125°C, -55°C	2	17	ns

NOTES:

1. All voltages referenced to device GND.
2. AC measurements assume  $RL = 500\Omega$ ,  $CL = 50\text{pF}$ , Input TR = TF = 3ns,  $VIL = \text{GND}$ ,  $VIH = \text{VCC}$ .

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS

PARAMETER	SYMBOL	(NOTE 1) CONDITIONS	TEMPERATURE	LIMITS		UNITS
				MIN	MAX	
Capacitance Power Dissipation	CPD	VCC = 5.0V, f = 1MHz	+25°C	-	45	pF
			+125°C, -55°C	-	56	pF
Input Capacitance	CIN	VCC = 5.0V, f = 1MHz	+25°C	-	10	pF
			+125°C, -55°C	-	10	pF
Output Transition Time	TTHL TTLH	VCC = 4.5V	+25°C	-	12	ns
			+125°C, -55°C	-	18	ns

NOTE:

1. The parameters listed in Table 3 are controlled via design or process parameters. Min and Max Limits are guaranteed but not directly tested. These parameters are characterized upon initial design release and upon design changes which affect these characteristics..

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TABLE 4. DC POST RADIATION ELECTRICAL PERFORMANCE CHARACTERISTICS

PARAMETER	SYMBOL	(NOTES 1, 2) CONDITIONS	TEMPERATURE	200K RAD LIMITS		UNITS
				MIN	MAX	
Quiescent Current	ICC	VCC = 5.5V, VIN = VCC or GND	+25°C	-	0.75	mA
Output Current (Sink)	IOL	VCC = 4.5V, VIN = VCC or GND, VOUT = 0.4V	+25°C	6.0	-	mA
Output Current (Source)	IOH	VCC = 4.5V, VIN = VCC or GND, VOUT = VCC -0.4V	+25°C	-6.0	-	mA
Output Voltage Low	VOL	VCC = 4.5V and 5.5V, VIH = 0.70(VCC), VIL = 0.30(VCC), IOL = 50µA	+25°C	-	0.1	V
Output Voltage High	VOH	VCC = 4.5V and 5.5V, VIH = 0.70(VCC), VIL = 0.30(VCC), IOH = -50µA	+25°C	VCC -0.1	-	V
Input Leakage Current	IIN	VCC = 5.5V, VIN = VCC or GND	+25°C	-	±5	µA
Three-State Output Leakage Current	IOZ	Applied Voltage = 0V or VCC, VCC = 5.5V	+25°C	-	±50	µA
Noise Immunity Functional Test	FN	VCC = 4.5V, VIH = 0.70(VCC), VIL = 0.30(VCC), (Note 3)	+25°C	-	-	-
Select to Output	TPHL	VCC = 4.5V	+25°C	2	31	ns
	TPLH	VCC = 4.5V	+25°C	2	31	ns
Data to Output	TPHL	VCC = 4.5V	+25°C	2	22	ns
	TPLH	VCC = 4.5V	+25°C	2	24	ns
Enable to Output	TPZL	VCC = 4.5V	+25°C	2	17	ns
	TPZH	VCC = 4.5V	+25°C	2	20	ns
Disable to Output	TPHZ	VCC = 4.5V	+25°C	2	19	ns
	TPLZ	VCC = 4.5V	+25°C	2	17	ns

NOTES:

1. All voltages referenced to device GND.
2. AC measurements assume RL = 500Ω, CL = 50pF, Input TR = TF = 3ns, VIL = GND, VIH = VCC
3. For functional tests VO  $\geq$  4.0V is recognized as a logic "1", and VO  $\leq$  0.5V is recognized as a logic "0".

TABLE 5. BURN-IN AND OPERATING LIFE TEST, DELTA PARAMETERS (+25°C)

PARAMETER	GROUP B SUBGROUP	DELTA LIMIT
ICC	5	12µA
IOL/IOH	5	-15% of 0 Hour
IOZL/IOZH	5	±200nA

## Specifications HCS253MS

TABLE 6. APPLICABLE SUBGROUPS

CONFORMANCE GROUPS		METHOD	GROUP A SUBGROUPS	READ AND RECORD
Initial Test (Preburn-In)		100%/5004	1, 7, 9	ICC, IOL/H
Interim Test I (Postburn-In)		100%/5004	1, 7, 9	ICC, IOL/H
Interim Test II (Postburn-In)		100%/5004	1, 7, 9	ICC, IOL/H
PDA		100%/5004	1, 7, 9, Deltas	
Interim Test III (Postburn-In)		100%/5004	1, 7, 9	ICC, IOL/H
PDA		100%/5004	1, 7, 9, Deltas	
Final Test		100%/5004	2, 3, 8A, 8B, 10, 11	
Group A (Note 1)		Sample/5005	1, 2, 3, 7, 8A, 8B, 9, 10, 11	
Group B	Subgroup B-5	Sample/5005	1, 2, 3, 7, 8A, 8B, 9, 10, 11, Deltas	Subgroups 1, 2, 3, 9, 10, 11, (Note 2)
	Subgroup B-6	Sample/5005	1, 7, 9	
Group D		Sample/5005	1, 7, 9	

NOTES:

1. Alternate group A inspection in accordance with Method 5005 of MIL-STD-883 may be exercised.
2. Table 5 parameters only.

TABLE 7. TOTAL DOSE IRRADIATION

CONFORMANCE GROUPS	METHOD	TEST		READ AND RECORD	
		PRE RAD	POST RAD	PRE RAD	POST RAD
Group E Subgroup 2	5005	1, 7, 9	Table 4	1, 9	Table 4 (Note 1)

NOTE:

1. Except FN test which will be performed 100% Go/No-Go.

TABLE 8. STATIC AND DYNAMIC BURN-IN TEST CONNECTIONS

OPEN	GROUND	1/2 VCC = 3V $\pm$ 0.5V	VCC = 6V $\pm$ 0.5V	OSCILLATOR	
				50kHz	25kHz
STATIC BURN-IN I TEST CONNECTIONS (Note 1)					
7, 9	1 - 6, 8, 10 - 15	-	16	-	-
STATIC BURN-IN II TEST CONNECTIONS (Note 1)					
7, 9	8	-	1 - 6, 10 - 16	-	-
DYNAMIC BURN-IN TEST CONNECTIONS (Note 2)					
-	1, 8, 15	7, 9	16	3 - 6, 10 - 14	2

NOTES:

1. Each pin except VCC and GND will have a resistor of  $10K\Omega \pm 5\%$  for static burn-in
2. Each pin except VCC and GND will have a resistor of  $680\Omega \pm 5\%$  for dynamic burn-in

TABEL 9. IRRADIATION TEST CONNECTIONS

OPEN	GROUND	VCC = 5V $\pm$ 0.5V
7, 9	8	1 - 6, 10 - 16

NOTE: Each pin except VCC and GND will have a resistor of  $47K\Omega \pm 5\%$  for irradiation testing.  
Group E, Subgroup 2, sample size is 4 dice/wafer 0 failures.

## HCS253MS

### ***Intersil Space Level Product Flow - 'MS'***

Wafer Lot Acceptance (All Lots) Method 5007 (Includes SEM)	100% Interim Electrical Test 1 (T1)
GAMMA Radiation Verification (Each Wafer) Method 1019, 4 Samples/Wafer, 0 Rejects	100% Delta Calculation (T0-T1)
100% Nondestructive Bond Pull, Method 2023	100% Static Burn-In 2, Condition A or B, 24 hrs. min., +125°C min., Method 1015
Sample - Wire Bond Pull Monitor, Method 2011	100% Interim Electrical Test 2 (T2)
Sample - Die Shear Monitor, Method 2019 or 2027	100% Delta Calculation (T0-T2)
100% Internal Visual Inspection, Method 2010, Condition A	100% PDA 1, Method 5004 (Notes 1and 2)
100% Temperature Cycle, Method 1010, Condition C, 10 Cycles	100% Dynamic Burn-In, Condition D, 240 hrs., +125°C or Equivalent, Method 1015
100% Constant Acceleration, Method 2001, Condition per Method 5004	100% Interim Electrical Test 3 (T3)
100% PIND, Method 2020, Condition A	100% Delta Calculation (T0-T3)
100% External Visual	100% PDA 2, Method 5004 (Note 2)
100% Serialization	100% Final Electrical Test
100% Initial Electrical Test (T0)	100% Fine/Gross Leak, Method 1014
100% Static Burn-In 1, Condition A or B, 24 hrs. min., +125°C min., Method 1015	100% Radiographic, Method 2012 (Note 3)
	100% External Visual, Method 2009
	Sample - Group A, Method 5005 (Note 4)
	100% Data Package Generation (Note 5)

#### NOTES:

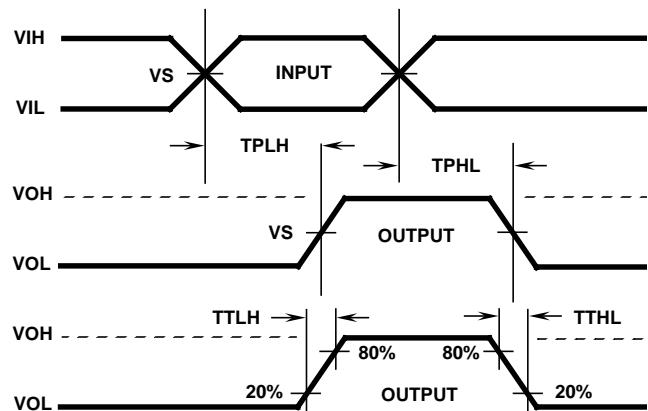
1. Failures from Interim electrical test 1 and 2 are combined for determining PDA 1.
2. Failures from subgroup 1, 7, 9 and deltas are used for calculating PDA. The maximum allowable PDA = 5% with no more than 3% of the failures from subgroup 7.
3. Radiographic (X-Ray) inspection may be performed at any point after serialization as allowed by Method 5004.
4. Alternate Group A testing may be performed as allowed by MIL-STD-883, Method 5005.

#### 5. Data Package Contents:

- Cover Sheet (Intersil Name and/or Logo, P.O. Number, Customer Part Number, Lot Date Code, Intersil Part Number, Lot Number, Quantity).
- Wafer Lot Acceptance Report (Method 5007). Includes reproductions of SEM photos with percent of step coverage.
- GAMMA Radiation Report. Contains Cover page, disposition, Rad Dose, Lot Number, Test Package used, Specification Numbers, Test equipment, etc. Radiation Read and Record data on file at Intersil.
- X-Ray report and film. Includes penetrometer measurements.
- Screening, Electrical, and Group A attributes (Screening attributes begin after package seal).
- Lot Serial Number Sheet (Good units serial number and lot number).
- Variables Data (All Delta operations). Data is identified by serial number. Data header includes lot number and date of test.
- The Certificate of Conformance is a part of the shipping invoice and is not part of the Data Book. The Certificate of Conformance is signed by an authorized Quality Representative.

# HCS253MS

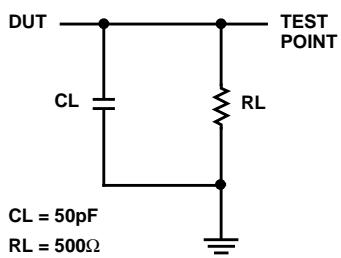
## AC Timing Diagrams



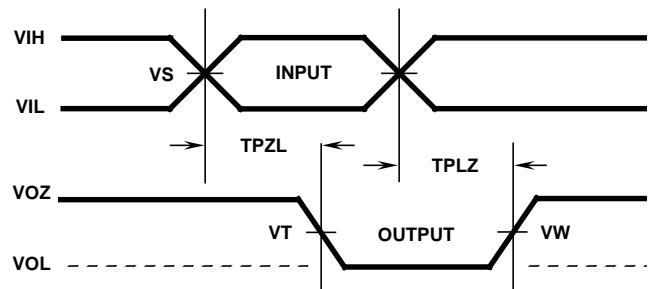
### AC VOLTAGE LEVELS

PARAMETER	HCS	UNITS
VCC	4.50	V
VIH	4.50	V
VS	2.25	V
VIL	0	V
GND	0	V

## AC Load Circuit



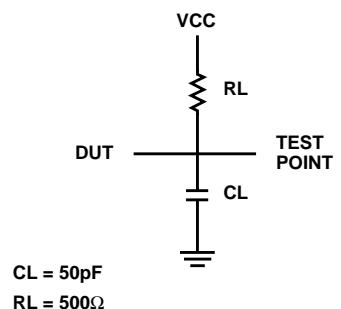
## Three-State Low Timing Diagrams



### THREE-STATE LOW VOLTAGE LEVELS

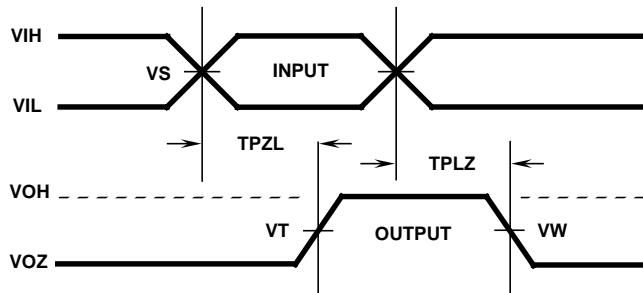
PARAMETER	HCS	UNITS
VCC	4.50	V
VIH	4.50	V
VS	2.25	V
VT	2.25	V
VW	0.90	V
GND	0	V

## Three-State Low Load Circuit



## HCS253MS

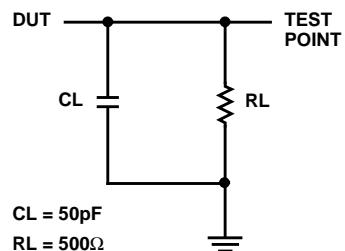
### Three-State High Timing Diagrams



THREE-STATE HIGH VOLTAGE LEVELS

PARAMETER	HCS	UNITS
VCC	4.50	V
VIH	4.50	V
VS	2.25	V
VT	2.25	V
VW	3.60	V
GND	0	V

### Three-State High Load Circuit



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# HCS253MS

## Die Characteristics

### DIE DIMENSIONS:

84 x 84 mils

### METALLIZATION:

Type: AlSi

Metal Thickness:  $11\text{k}\text{\AA} \pm 1\text{k}\text{\AA}$

### GLASSIVATION:

Type:  $\text{SiO}_2$

Thickness:  $13\text{k}\text{\AA} \pm 2.6\text{k}\text{\AA}$

### WORST CASE CURRENT DENSITY:

$<2.0 \times 10^5\text{A/cm}^2$

### BOND PAD SIZE:

$100\mu\text{m} \times 100\mu\text{m}$

4 mils x 4 mils

## Metallization Mask Layout

HCS253MS

